

HXT6112

12-Channel 16Gb/s VCSEL Driver

Description

The HXT6112 VCSEL driver array is a key component for compact, robust, low-power optical transmitter modules. In conjunction with the VCSEL array, the chip handles the complete digital-to-optical conversion, including CML input, laser driver, drive control, and supervision. Standard silicon technology and a small number of additional components allow for cost-effective and compact assemblies.

Applications

- IEEE 802.3ba Ethernet transceivers
- InfiniBand QDR and FDR active cables
- Proprietary multi-channel optical modules

Features

- Low power consumption of 46mW per channel while delivering 5mA average and 5mA modulation current
- Compatible with common cathode and isolated VCSEL arrays
- 2-wire interface control and symmetric pad design maximize module design flexibility
- 10mA average and 10mA modulation current maximum
- 15mA burn-in current maximum
- InfiniBand QDR/FDR compliant

Ordering Information

Part	Temperature Range	Pin-Package
HXT6112-DNT	0°C to +85°C	Bare Die 2.05 × 3.65 mm
HXT6112-EVB	Room Temperature	Evaluation Board

For price, delivery schedules, and to place orders, contact Renesas [sales](#).

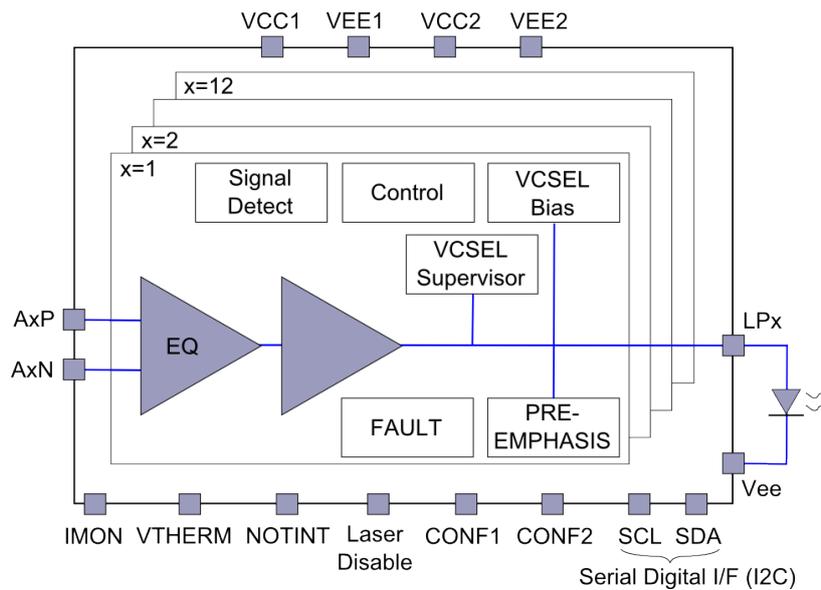


Figure 1. Device Diagram

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